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Dimensions

Chip Size	1812
L	4.52mm +0.94/-0.3mm (0.178 in +0.037/-0.012 in)
W	3.2mm +0.68/-0.3mm (0.126 in +0.027/-0.012 in)
T	2.79mm MAX (0.11 in MAX)
B	0.61mm +/-0.46mm (0.024 in +/-0.018 in)

Packaging Specifications

Packaging	Waffle
Packaging Quantity	42

General Information

Series	SMD MIL BP PRF32535
Style	SMD Chip
Description	SMD, Low ESR, MIL-PRF-32535
RoHS	No
Prop 65	⚠ WARNING: Cancer and reproductive harm - http://www.p65warnings.ca.gov
SCIP Number	Oa998f97-a584-44f1-9938-b8ffafe99340
Termination	Solder Dipped
Failure Rate	N/A
Qualifications	MIL-PRF-32535 T-Level
AEC-Q200	No
Shelf Life	78 Weeks
MSL	1

Specifications

Capacitance	0.015 uF
Capacitance Tolerance	1%
Voltage DC	50 VDC
Dielectric Withstanding Voltage	125 VDC
Temperature Range	-55/+125°C
Temperature Coefficient	BP
Dissipation Factor	0.25% 1 MHz 25C
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	66.67 GOhms

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